

September 2008

FDN5632N_F085

N-Channel Logic Level PowerTrench $^{\hbox{\scriptsize I}}$ MOSFET 60V, 1.6A, 98m Ω

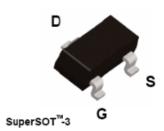
Features

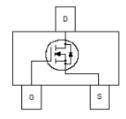
- \blacksquare R_{DS(on)} = 98m Ω at V_{GS} = 4.5V, I_D = 1.6A
- \blacksquare R_{DS(on)} = 82m Ω at V_{GS} = 10V, I_D = 1.7A
- Typ $Q_{g(TOT)} = 9.2nC$ at $V_{GS} = 10V$
- Low Miller Charge
- Qualified to AEC Q101
- RoHS Compliant

Applications

- DC/DC converter
- Motor Drives







Units

MOSFET Maximum Ratings $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	60	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (V _{GS} = 10V)	1.7	^
'D	Pulsed	10	Α
P_{D}	Power Dissipation	1.1	W
T_J , T_{STG}	Operating and Storage Temperature	-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	75	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-252, 1in ² copper pad area	111	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
5632	FDN5632N_F085	SSOT3	7"	8mm	3000 units

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics							
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0$	V	60	-	-	V
1	Zero Gate Voltage Drain Current	$V_{DS} = 48V$,		-	-	1	μА
I _{DSS} Zero Gate Voltage Drain Current		$V_{GS} = 0V$	$T_A = 125^{\circ}C$	-	-	250	μΑ
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min

Тур

Max

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1	2.0	3	V
r _{DS(on)}		$I_D = 1.7A, V_{GS} = 10V$	-	57	82	
	Drain to Source On Resistance	$I_D = 1.6A, V_{GS} = 6V$	-	62	88	
		$I_D = 1.6A, V_{GS} = 4.5V$		70	98	mΩ
		$I_D = 1.7A$, $V_{GS} = 10V$, $T_A = 150^{\circ}C$	-	107	135	

Dynamic Characteristics

C _{iss}	Input Capacitance	\\ 45\\\\\	$V_{DS} = 15V, V_{GS} = 0V,$		475	-	pF
Coss	Output Capacitance	$V_{DS} = 15V, V_{GS} = 100$			60	-	pF
C _{rss}	Reverse Transfer Capacitance	1 = 1101112		-	30	-	pF
R_G	Gate Resistance	f = 1MHz	f = 1MHz		1.4	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	.,	-	9.2	12	nC
Q _{gs}	Gate to Source Gate Charge		$V_{DD} = 20V$ $I_{D} = 1.7A$	-	1.5	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		ID = 1.77	-	1.4	-	nC

Units

ns

Max

12.9

Electrical Characteristics $T_A = 25^{\circ}C$ unless otherwise noted

Parameter

Switc	Switching Characteristics							
t _{on}	Turn-On Time		-	-	30	ns		
t _{d(on)}	Turn-On Delay Time		-	15	-	ns		
t _r	Rise Time	$V_{DD} = 30V, I_{D} = 1.0A$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	-	1.7	-	ns		
t _{d(off)}	Turn-Off Delay Time	$v_{GS} = 10v, R_{GEN} = 602$	-	5.2	-	ns		
t _f	Fall Time		-	1.3	-	ns		

Test Conditions

Min

Тур

Drain-Source Diode Characteristics

Turn-Off Time

Symbol

V _{SD}	Source to Drain Diode Voltage $\frac{I_{SD} = 1.7A}{I_{SD} = 0.85A}$	-	0.8	1.25	\/	
		$I_{SD} = 0.85A$	-	0.8	1.0	V
t _{rr}	Reverse Recovery Time	1 7 dl /dt 100 / / / 2	-	16.0	21	ns
Q _{rr}	Reverse Recovery Charge	$I_{SD} = 1.7A$, $dI_{SD}/dt = 100A/\mu s$	-	7.9	10.3	nC

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

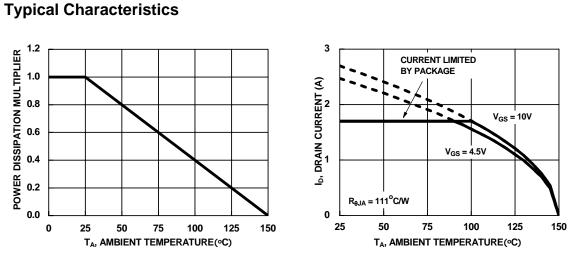


Figure 1. Normalized Power Dissipation vs Ambient Temperature

Figure 2. Maximum Continuous Drain Current vs
Ambient Temperature

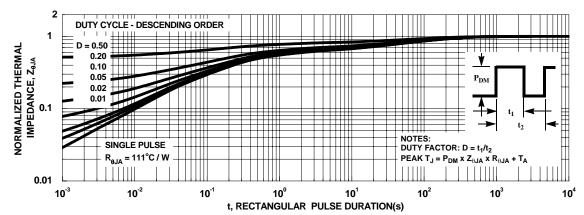


Figure 3. Normalized Maximum Transient Thermal Impedance

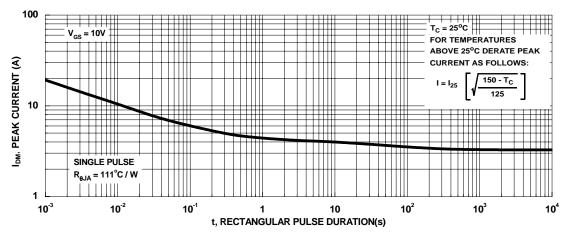


Figure 4. Peak Current Capability

Typical Characteristics

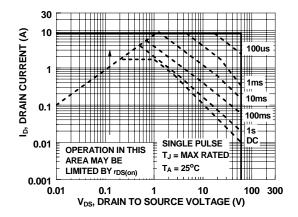


Figure 5. Forward Bias Safe Operating Area

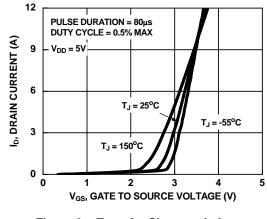


Figure 6. Transfer Characteristics

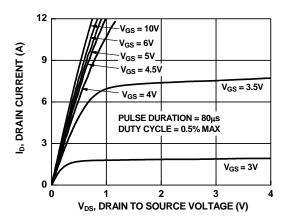


Figure 7. Saturation Characteristics

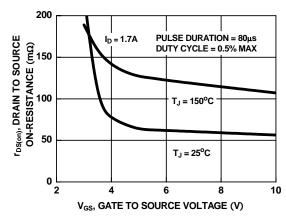


Figure 8. Drain to Source On-Resistance Variation vs Gate to Source Voltage

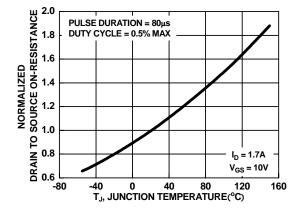


Figure 9. Normalized Drain to Source On Resistance vs Junction Temperature

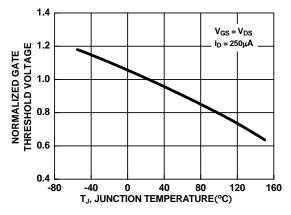


Figure 10. Normalized Gate Threshold Voltage vs Junction Temperature

Typical Characteristics

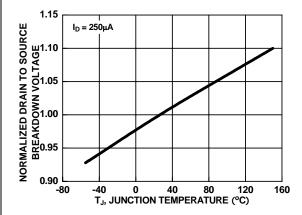


Figure 11. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

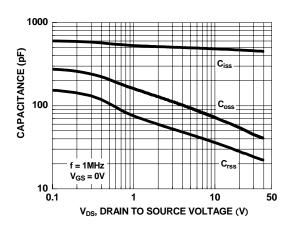


Figure 12. Capacitance vs Drain to Source Voltage

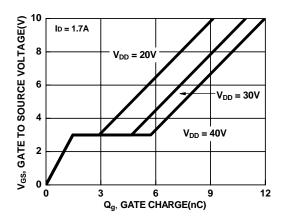


Figure 13. Gate Charge vs Gate to Source Voltage





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Definition of Terms		
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